

Appl. No. 10/711,795
Amdt. dated December 22, 2005
Reply to Office action of November 23, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1 (original): A printed circuit board (PCB) comprising:

5 a plastic substrate; and

a circuit layout formed on the plastic substrate, having a first layout and a second layout,

wherein the second layout comprises a pseudo-layout to prevent the PCB from being bent when heated.

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2 (original): The PCB of claim 1 wherein density of circuits of the second layout has a lower circuit density than that of the first layout.

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3 (currently amended): The PCB of claim 1 wherein the circuit layout comprises signal traces and power traces, and the pseudo-layout is isolated from the signal traces and the power traces on the PCB.

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4 (original): The PCB of claim 1 wherein the pseudo-layout comprises a plurality of pseudo-traces neither for power nor signal transmission.

5 (original): The PCB of claim 3 wherein the pseudo-traces are parallel to each other in a netlike structure.

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6 (currently amended): The PCB of claim 5 wherein the parallel pseudo-traces having have an interval distance, the interval distance is of 5mil.

7 (currently amended): The PCB of claim 5 wherein the width of the pseudo-traces is

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8-13 (cancelled).

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